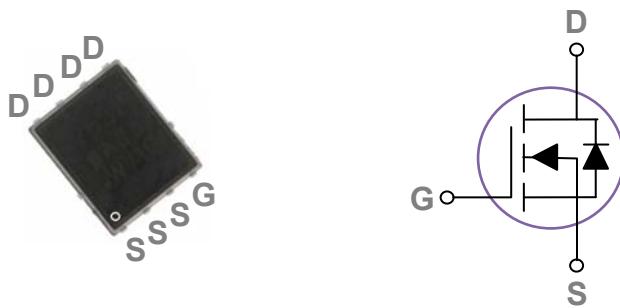


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK5X6 Pin Configuration



BVDSS	RDS(ON)	ID
100V	13mΩ	60A

### Features

- 100V,60A, RDS(ON) =13mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	60	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	38	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	240	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	205	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	64	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	142	W
	Power Dissipation – Derate above 25°C	1.14	W/°C
$T_{STG}$	Storage Temperature Range	-50 to 150	°C
$T_J$	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	0.88	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.05	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=15\text{A}$	---	11	13	$\text{m}\Omega$
		$V_{\text{GS}}=6\text{V}$ , $I_D=10\text{A}$	---	11.5	14	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=8\text{A}$	---	12.5	18	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1	2	3	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-5	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=3\text{A}$	---	10	---	S

**Dynamic and switching Characteristics**

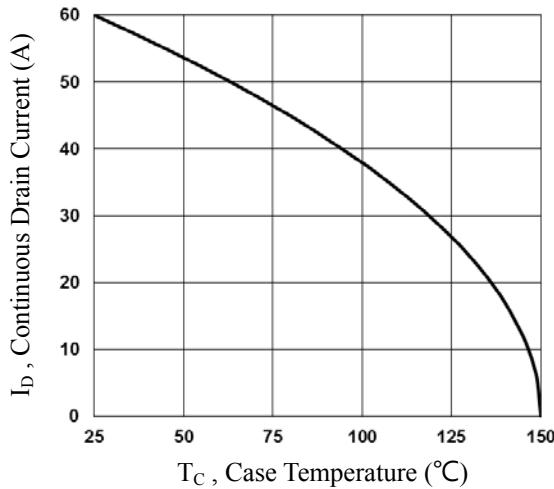
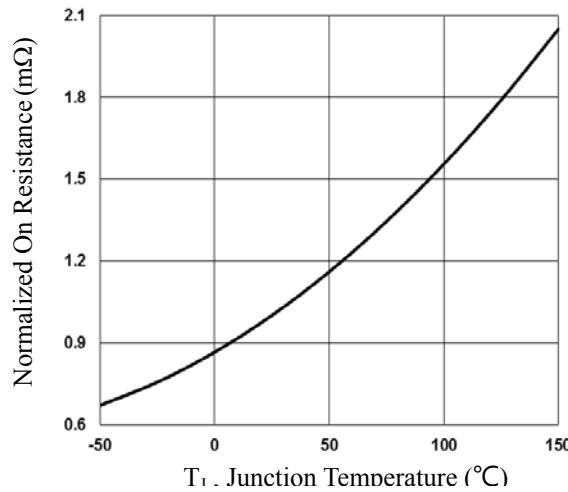
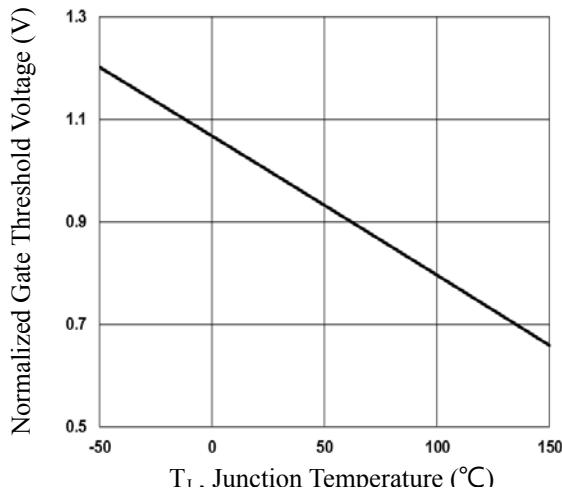
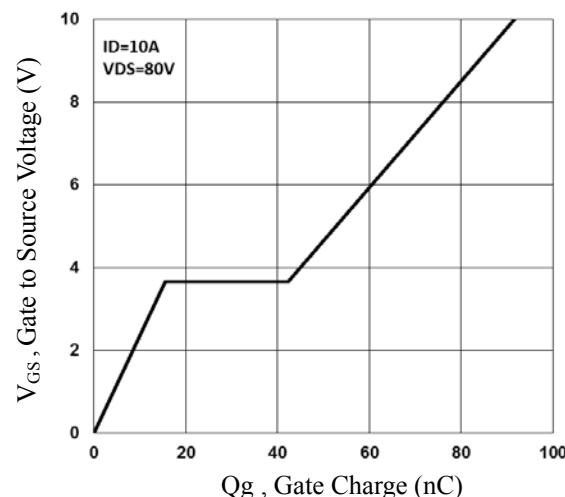
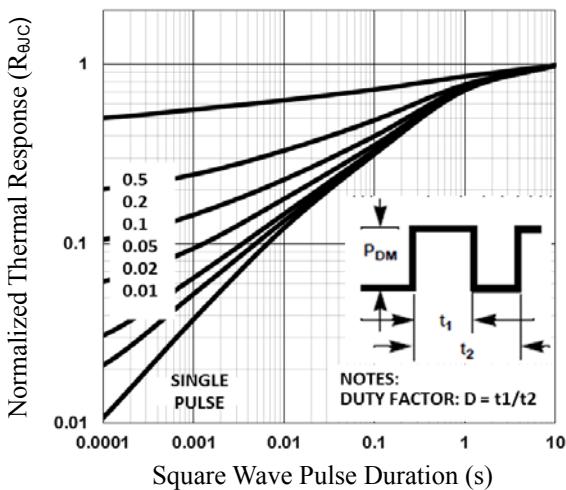
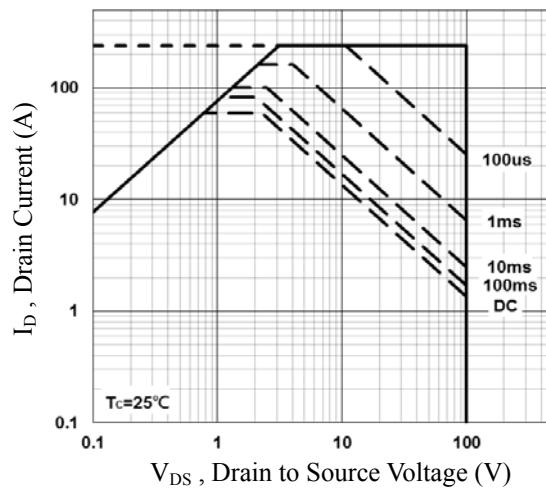
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	47.2	85	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	15.6	30	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	26.8	52	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ $I_D=1\text{A}$	---	35	70	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	23	46	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	67	135	
$T_f$	Fall Time <sup>3, 4</sup>		---	38	76	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	5775	8500	pF
$C_{\text{oss}}$	Output Capacitance		---	317	460	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	115	180	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.2	2.4	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	60	A
$I_{\text{SM}}$	Pulsed Source Current		---	---	120	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=64\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1** Continuous Drain Current vs. T<sub>c</sub>

**Fig.2** Normalized R<sub>DS(on)</sub> vs. T<sub>j</sub>

**Fig.3** Normalized V<sub>th</sub> vs. T<sub>j</sub>

**Fig.4** Gate Charge Characteristics

**Fig.5** Normalized Transient Impedance

**Fig.6** Maximum Safe Operation Area

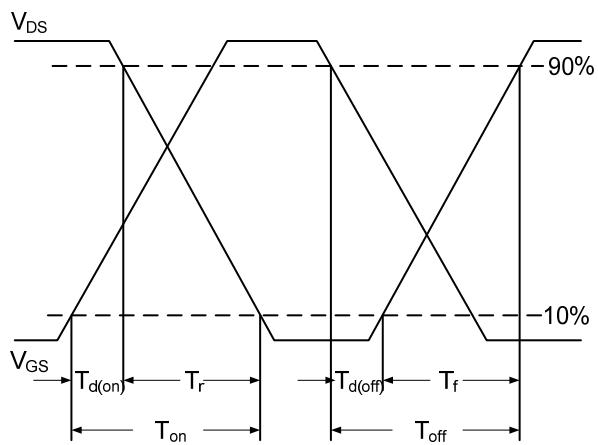


Fig.7 Switching Time Waveform

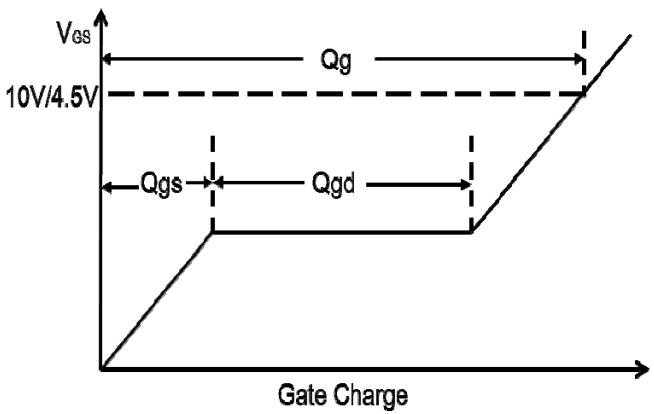
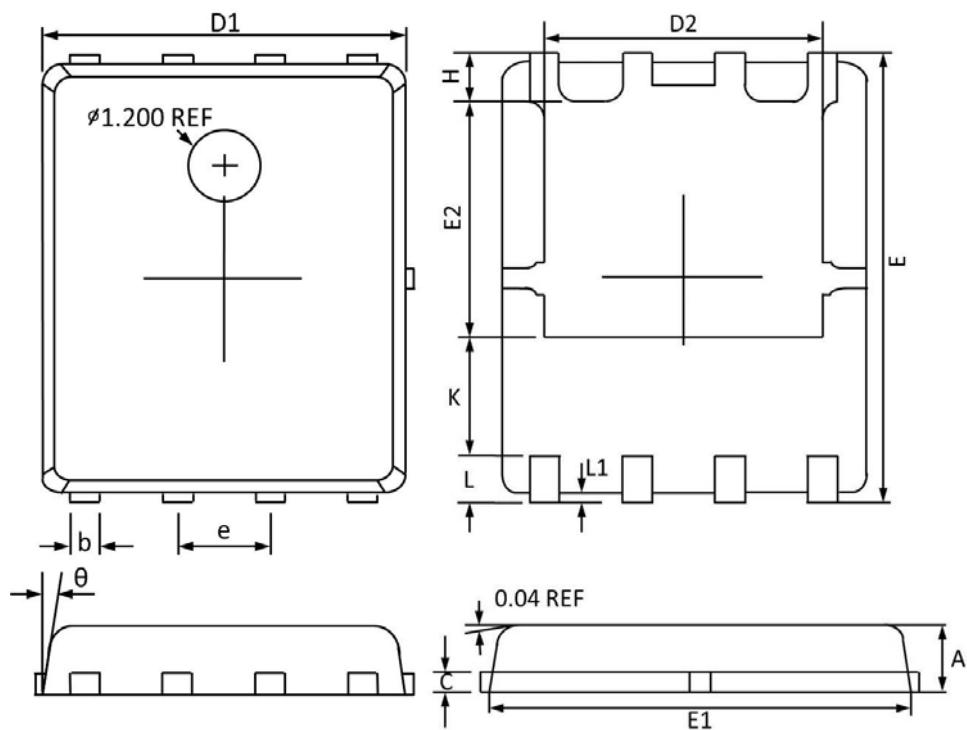


Fig.8 Gate Charge Waveform

## PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°